

AP4415GH-VB Datasheet P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d	Q _g (Typ.)			
- 30	0.033 at V _{GS} = - 10 V	- 38	19 nC			
- 30	0.046 at V _{GS} = - 4.5 V	- 25	19110			

FEATURES

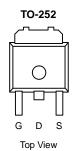
- Halogen-free
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

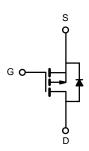


RoHS

APPLICATIONS

- Load Switch
- · Notebook Adaptor Switch





P-Channel MOSFET

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage	V _{GS}	± 20	V	
	T _C = 25 °C		- 38	
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 70 °C	1 . –	- 25	
Continuous Diam Current (1) = 130 °C)	T _A = 25 °C	I _D	- 14.9 ^{a, b}	
	T _A = 70 °C	1	- 13.6 ^{a, b}	A
Pulsed Drain Current	I _{DM}	- 112	A	
Continuous Source-Drain Diode Current	T _C = 25 °C		- 4.1	
Continuous Source-Drain Diode Current	T _A = 25 °C	l _S	- 2.2 ^{a, b}	
Avalanche Current	1 0411	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
	T _C = 25 °C		25	
Maximum Dawan Disaination	T _C = 70 °C		20	w
Maximum Power Dissipation	T _A = 25 °C	P _D	2.7 ^{a, b}	VV
	T _A = 70 °C		1.7 ^{a, b}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	6/ **	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on T_C = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 34		mV/
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			5.3		°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA
Zara Cata Valtaga Drain Current	1	V _{DS} = - 30 V, V _{GS} = 0 V V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 1	μΑ
Zero Gate Voltage Drain Current	IDSS				- 5	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α
David Course Co Otata Basista and	D	V _{GS} = - 10 V, I _D = - 10 A		0.033		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 8 A		0.046		Ω
prward Transconductance ^a g_{fs} $V_{DS} = -10 \text{ V}, I_D = -10 \text{ A}$			28		S	
Dynamic ^b						
Input Capacitance	C _{iss}			1350		pF
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		255		
Reverse Transfer Capacitance	C _{rss}			190		
Tatal Oata Obarra	Q_g $V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -1$	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -10 \text{ A}$		27	43	
Total Gate Charge				19	25	0
Gate-Source Charge	Q_{gs} $V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -10 \text{ A}$			6		nC
Gate-Drain Charge	Q _{gd}			12		1
Gate Resistance	R _g	f = 1 MHz	0.5	2.2	4.4	Ω
Turn-On Delay Time	t _{d(on)}			13	25	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		12	24	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		40	70	
Fall Time	t _f			9	18	
Turn-On Delay Time	t _{d(on)}			48	80	ns
Rise Time	ì,	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		92	160	7
urn-Off DelayTime t _{d(off)}		$I_{D} \cong -10 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_{g} = 1 \Omega$		34	60	1
Fall Time	t _f	1		19	35	
Drain-Source Body Diode Characteris	tics					
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.1	
Pulse Diode Forward Current	I _{SM}	-			- 40	_ A
Body Diode Voltage	V _{SD}	I _S = - 3 A, V _{GS} = 0 V		- 0.75	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			27	45	ns
Body Diode Reverse Recovery Charge	Q _{rr}	1 40 A 41/44 400 A/45 T 25 20		16	27	nC
Reverse Recovery Fall Time	t _a	$I_F = -10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		12		_
Reverse Recovery Rise Time	t _b	1		15		ns

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

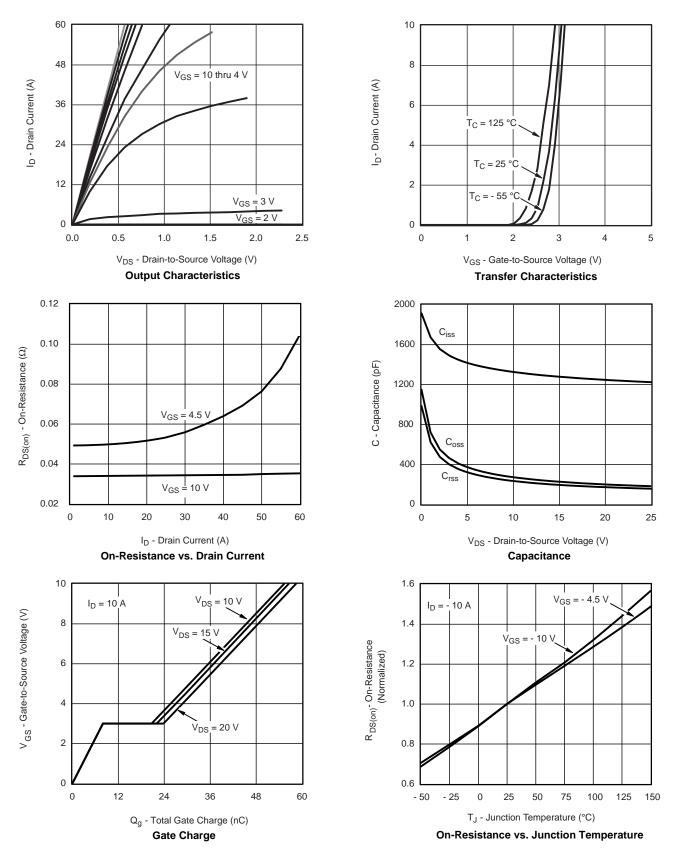
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a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

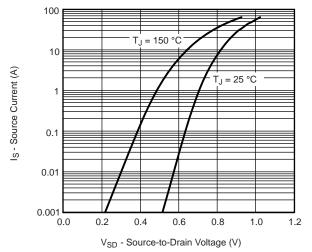


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

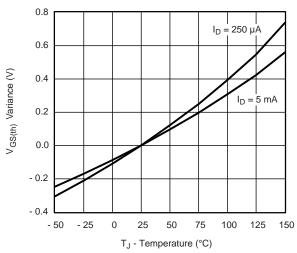




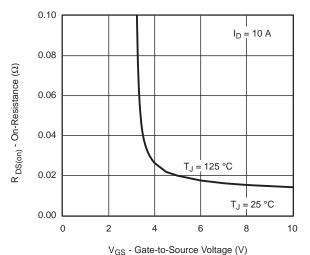
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



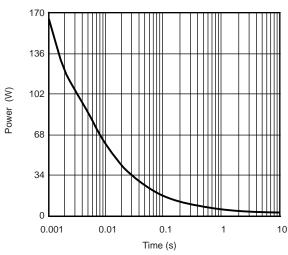
Source-Drain Diode Forward Voltage



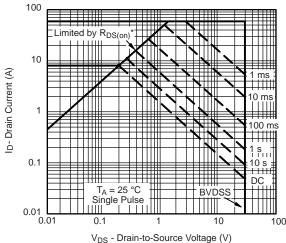
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

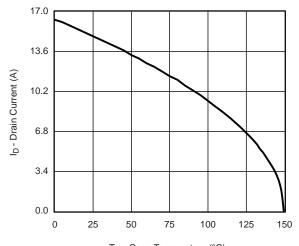


* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

Safe Operating Area

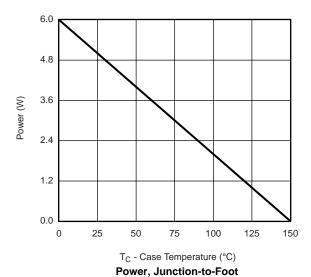


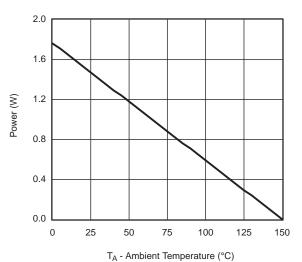
MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



 $T_{\mbox{\scriptsize C}}$ - Case Temperature (°C)

Current Derating*





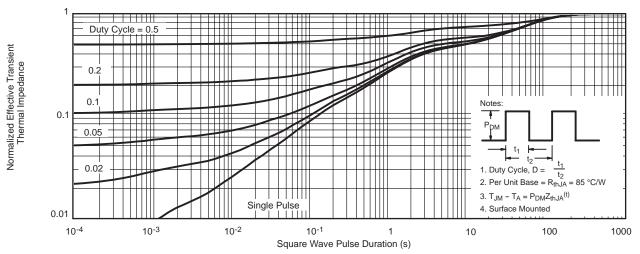
Power Derating, Junction-to-Ambient

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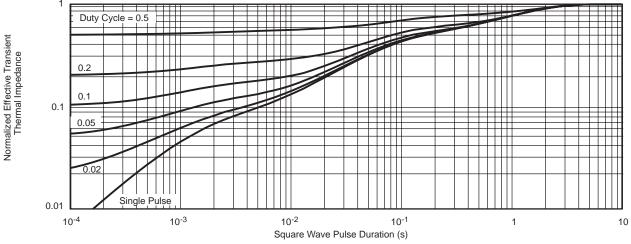
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



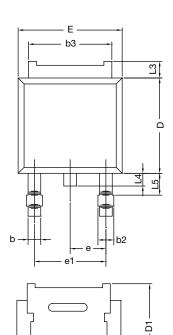
Normalized Thermal Transient Impedance, Junction-to-Ambient



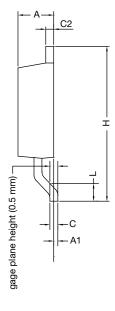
Normalized Thermal Transient Impedance, Junction-to-Foot



TO-252AA CASE OUTLINE



E1



	MILLIN	METERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	1	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28 BSC		0.090 BSC		
e1	4.56	4.56 BSC		BSC	
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-	0247-Rev. M,	24-Dec-12			

ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347

Note

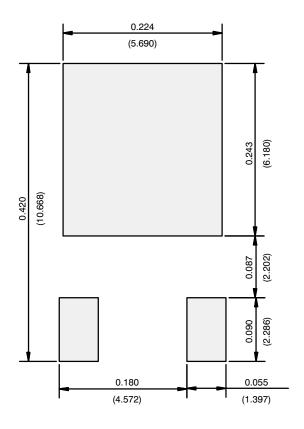
• Dimension L3 is for reference only.

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RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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